

# XC7WH126

Dual buffer/line driver; 3-state

Rev. 2 — 8 May 2013

Product data sheet

## 1. General description

The XC7WH126 is a high-speed Si-gate CMOS devices. This device provides a dual non-inverting buffer/line driver with 3-state output. The 3-state output is controlled by the output enable input (nOE). A LOW at nOE causes the output to assume a high-impedance OFF-state.

## 2. Features and benefits

- Symmetrical output impedance
- High noise immunity
- Low power dissipation
- Balanced propagation delays
- Multiple package options
- ESD protection:
  - ◆ HBM JESD22-A114E: exceeds 2000 V
  - ◆ MM JESD22-A115-A: exceeds 200 V
  - ◆ CDM JESD22-C101C: exceeds 1000 V
- Specified from -40 °C to +125 °C

## 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
XC7WH126DP	-40 °C to +125 °C	TSSOP8	plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm	SOT505-2
XC7WH126DC	-40 °C to +125 °C	VSSOP8	plastic very thin shrink small outline package; 8 leads; body width 2.3 mm	SOT765-1
XC7WH126GD	-40 °C to +125 °C	XSON8	plastic extremely thin small outline package; no leads; 8 terminals; body 3 × 2 × 0.5 mm	SOT996-2



## 4. Marking

Table 2. Marking codes

Type number	Marking <sup>[1]</sup>
XC7WH126DP	f26
XC7WH126DC	f26
XC7WH126GD	f26

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

## 5. Functional diagram

*mna946*

*mna947*

*mna234*

**Fig 1. Logic symbol**

**Fig 2. IEC logic symbol**

**Fig 3. Logic diagram (one buffer)**

## 6. Pinning information

### 6.1 Pinning

**XC7WH126**

*001aak067*

**XC7WH126**

Transparent top view

*001aak068*

**Fig 4. Pin configuration SOT505-2 (TSSOP8) and SOT765-1 (VSSOP8)**

**Fig 5. Pin configuration SOT996-2 (XSON8)**

## 6.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
1OE, 2OE	1, 7	output enable input (active LOW)
1A, 2A	2, 5	data input
GND	4	ground (0 V)
1Y, 2Y	6, 3	data output
V <sub>CC</sub>	8	supply voltage

## 7. Functional description

Table 4. Function table<sup>[1]</sup>

Control	Input	Output
nOE	nA	nY
H	L	L
H	H	H
L	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+7.0	V
V <sub>I</sub>	input voltage		-0.5	+7.0	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < -0.5 V	<sup>[1]</sup> -20	-	mA
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < -0.5 V or V <sub>O</sub> > V <sub>CC</sub> + 0.5 V	<sup>[1]</sup> -	±20	mA
I <sub>O</sub>	output current	-0.5 V < V <sub>O</sub> < V <sub>CC</sub> + 0.5 V	-	±25	mA
I <sub>CC</sub>	supply current		-	75	mA
I <sub>GND</sub>	ground current		-75	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C	<sup>[2]</sup> -	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For TSSOP8 package: above 55 °C the value of P<sub>tot</sub> derates linearly with 2.5 mW/K.  
 For VSSOP8 package: above 110 °C the value of P<sub>tot</sub> derates linearly with 8 mW/K.  
 For XSON8 package: above 118 °C the value of P<sub>tot</sub> derates linearly with 7.8 mW/K.

## 9. Recommended operating conditions

**Table 6. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>CC</sub>	supply voltage		2.0	5.0	5.5	V
V <sub>I</sub>	input voltage		0	-	5.5	V
V <sub>O</sub>	output voltage		0	-	V <sub>CC</sub>	V
T <sub>amb</sub>	ambient temperature		-40	+25	+125	°C
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 3.3 V ± 0.3 V	-	-	100	ns/V
		V <sub>CC</sub> = 5.0 V ± 0.5 V	-	-	20	ns/V

## 10. Static characteristics

**Table 7. Static characteristics**

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	-	-	1.5	-	1.5	-	V
		V <sub>CC</sub> = 3.0 V	2.1	-	-	2.1	-	2.1	-	V
		V <sub>CC</sub> = 5.5 V	3.85	-	-	3.85	-	3.85	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	-	0.5	-	0.5	-	0.5	V
		V <sub>CC</sub> = 3.0 V	-	-	0.9	-	0.9	-	0.9	V
		V <sub>CC</sub> = 5.5 V	-	-	1.65	-	1.65	-	1.65	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = -50 μA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -50 μA; V <sub>CC</sub> = 3.0 V	2.9	3.0	-	2.9	-	2.9	-	V
		I <sub>O</sub> = -50 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 3.0 V	2.58	-	-	2.48	-	2.40	-	V
		I <sub>O</sub> = -8.0 mA; V <sub>CC</sub> = 4.5 V	3.94	-	-	3.8	-	3.70	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 3.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.36	-	0.44	-	0.55	V
		I <sub>O</sub> = 8.0 mA; V <sub>CC</sub> = 4.5 V	-	-	0.36	-	0.44	-	0.55	V
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	0.25	-	2.5	-	10	μA
I <sub>I</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	1.0	-	10	-	40	μA
C <sub>I</sub>	input capacitance		-	1.5	10	-	10	-	10	pF

## 11. Dynamic characteristics

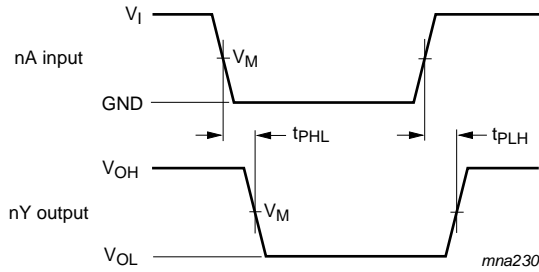
**Table 8. Dynamic characteristics**

$GND = 0 V$ ; for test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$t_{pd}$	propagation delay	nA to nY; see <a href="#">Figure 6</a>	[1]							
		$V_{CC} = 3.0 V$ to $3.6 V$	[2]							
		$C_L = 15 pF$	-	4.7	8.0	1.0	9.5	1.0	11.5	ns
		$C_L = 50 pF$	-	6.6	11.5	1.0	13.0	1.0	14.5	ns
		$V_{CC} = 4.5 V$ to $5.5 V$	[3]							
		$C_L = 15 pF$	-	3.4	5.5	1.0	6.5	1.0	7.0	ns
$t_{en}$	enable time	nOE to nY; see <a href="#">Figure 7</a>	[1]							
		$V_{CC} = 3.0 V$ to $3.6 V$	[2]							
		$C_L = 15 pF$	-	5.0	8.0	1.0	9.5	1.0	11.5	ns
		$C_L = 50 pF$	-	6.9	11.5	1.0	13.0	1.0	14.5	ns
		$V_{CC} = 4.5 V$ to $5.5 V$	[3]							
		$C_L = 15 pF$	-	3.6	5.1	1.0	6.0	1.0	6.5	ns
$t_{dis}$	disable time	nOE to nY; see <a href="#">Figure 7</a>	[1]							
		$V_{CC} = 3.0 V$ to $3.6 V$	[2]							
		$C_L = 15 pF$	-	6.0	9.7	1.0	11.5	1.0	12.5	ns
		$C_L = 50 pF$	-	8.3	13.2	1.0	15.0	1.0	16.5	ns
		$V_{CC} = 4.5 V$ to $5.5 V$	[3]							
		$C_L = 15 pF$	-	4.1	6.8	1.0	8.0	1.0	8.5	ns
$C_{PD}$	power dissipation capacitance	per buffer; $C_L = 50 pF$ ; $f_i = 1 MHz$ ; $V_i = GND$ to $V_{CC}$	[4]	-	10	-	-	-	-	pF

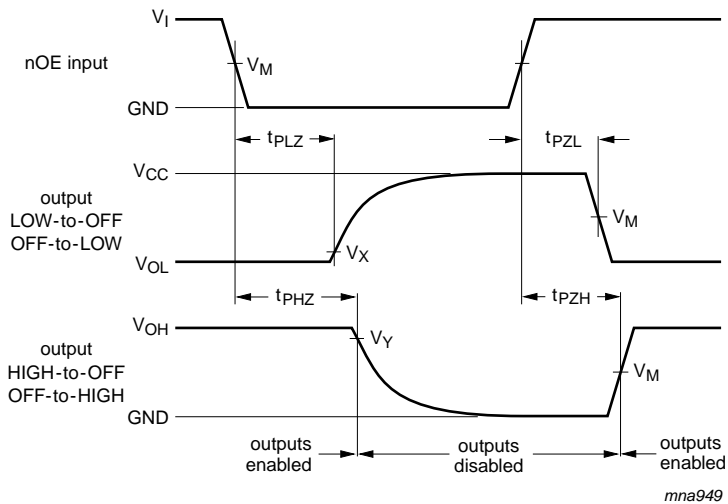
- [1]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .  
 $t_{en}$  is the same as  $t_{PZL}$  and  $t_{PZH}$ .  
 $t_{dis}$  is the same as  $t_{PLZ}$  and  $t_{PHZ}$ .
- [2] Typical values are measured at  $V_{CC} = 3.3 V$ .
- [3] Typical values are measured at  $V_{CC} = 5.0 V$ .
- [4]  $C_{PD}$  is used to determine the dynamic power dissipation  $P_D$  ( $\mu W$ ).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$  where:  
 $f_i$  = input frequency in MHz;  
 $f_o$  = output frequency in MHz;  
 $C_L$  = output load capacitance in pF;  
 $V_{CC}$  = supply voltage in Volts.

**12. Waveforms**



Measurement points are given in [Table 9](#).  
 Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 6. Input (nA) to output (nY) propagation delays**

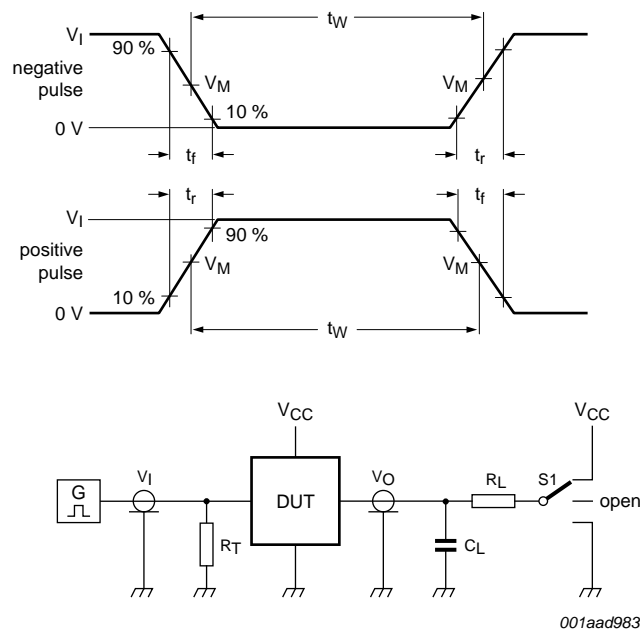


Measurement points are given in [Table 9](#).  
 Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 7. Enable and disable times**

**Table 9. Measurement points**

Type	Input	Output		
	$V_M$	$V_M$	$V_X$	$V_Y$
XC7WH126	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.3 V$	$V_{OH} - 0.3 V$



Test data is given in [Table 10](#).

Definitions test circuit:

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_L$  = Load resistance.

S1 = Test selection switch.

**Fig 8. Test circuit for measuring switching times**

**Table 10. Test data**

Type	Input		Load		S1 position		
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
XC7WH126	$V_{CC}$	$\leq 3$ ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$

13. Package outline

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm SOT505-2

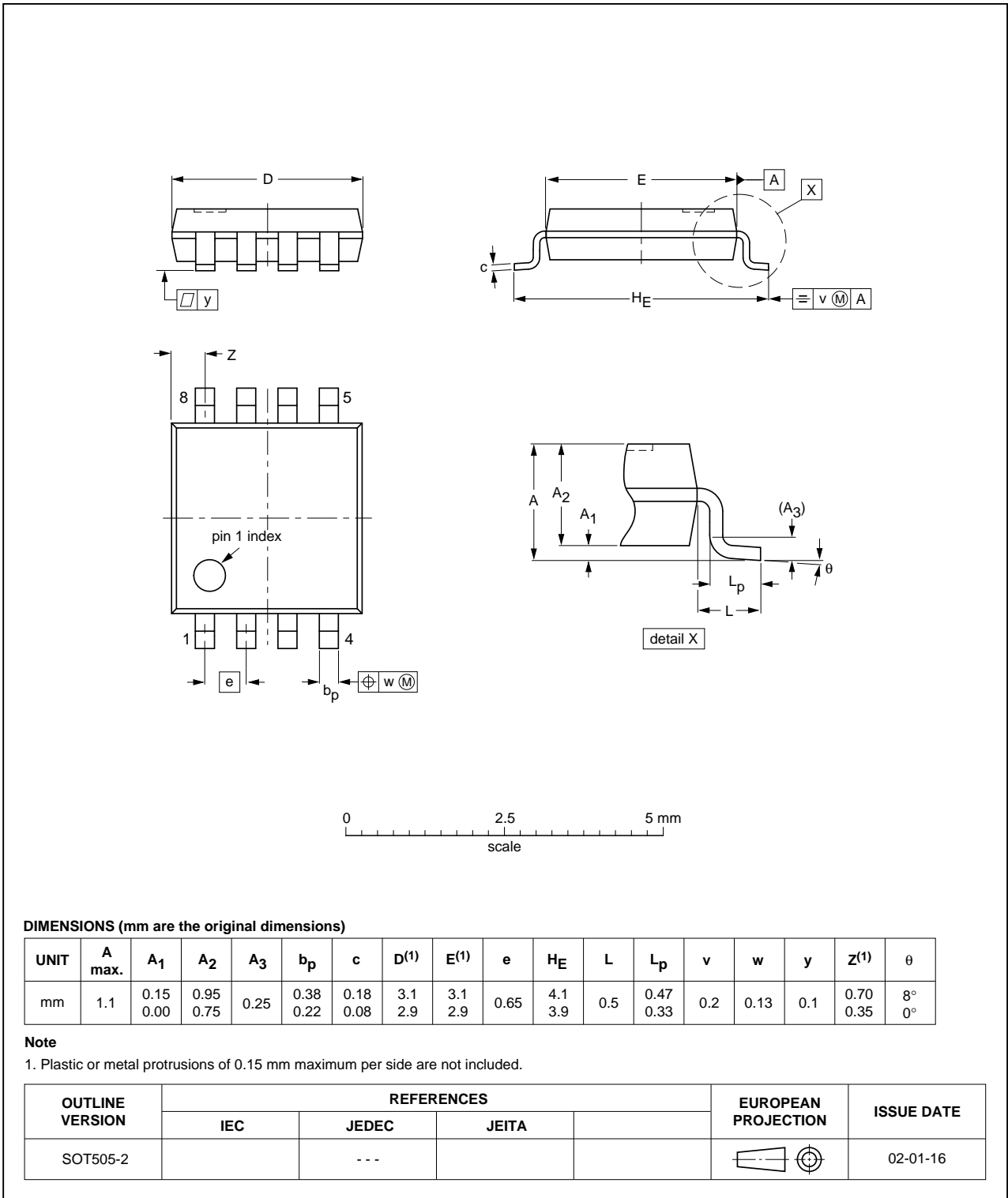


Fig 9. Package outline SOT505-2 (TSSOP8)



VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

SOT765-1

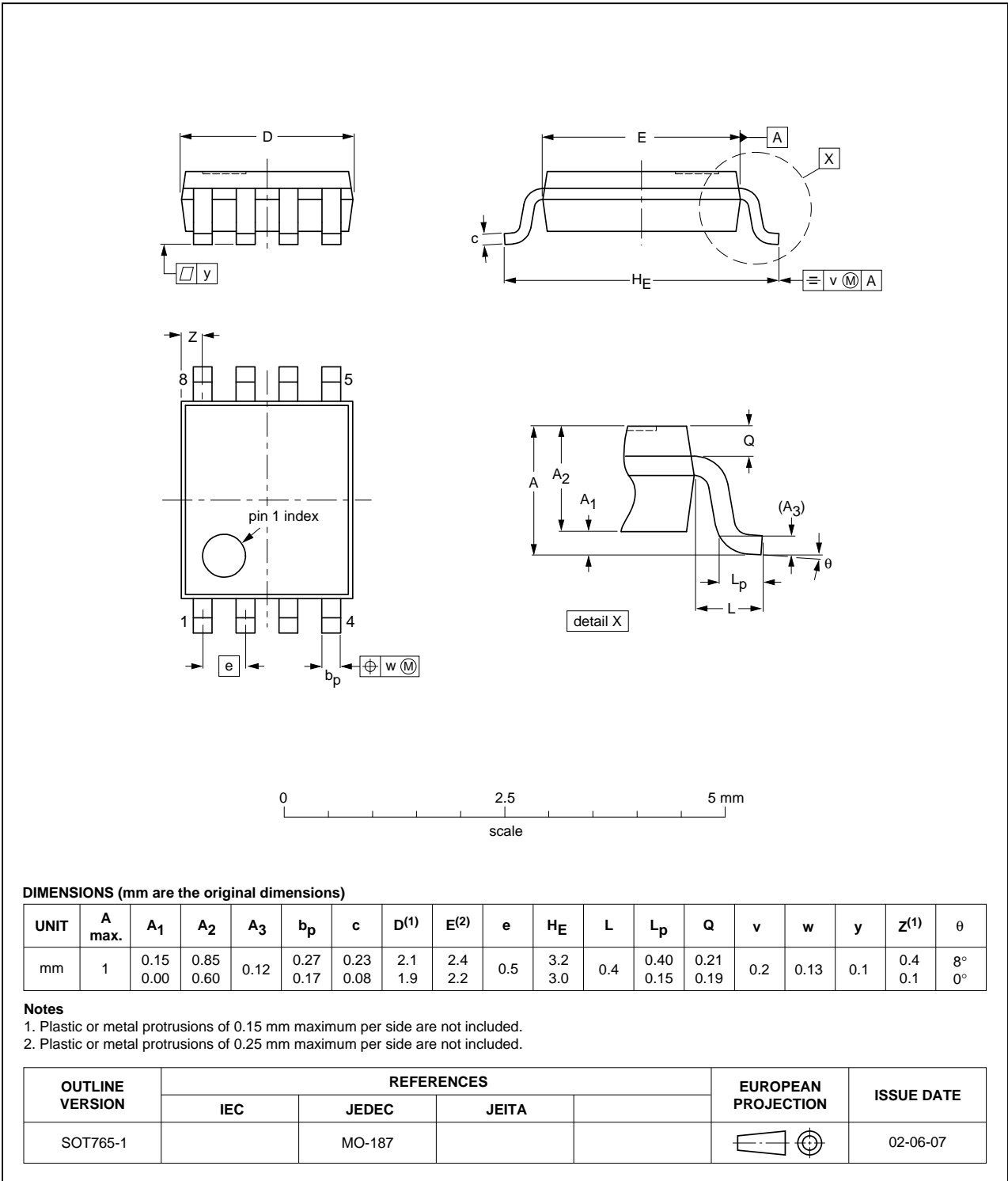


Fig 10. Package outline SOT765-1 (VSSOP8)

**XSON8: plastic extremely thin small outline package; no leads;  
8 terminals; body 3 x 2 x 0.5 mm**

**SOT996-2**



**Fig 11. Package outline SOT996-2 (XSON8)**

## 14. Abbreviations

Table 11. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
XC7WH126 v.2	20130508	Product data sheet	-	XC7WH126 v.1
Modifications:	• For type number XC7WH126GD XSON8U has changed to XSON8.			
XC7WH126 v.1	20090902	Product data sheet	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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